



## 2025 IEEE MTT-S International Microwave Workshop Series On Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2025)

July 23-26, 2025, Wuxi, China

<https://imws-amp.org>

**Call for Papers**



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#### Conference Secretariat:

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Jingyuan Zhang, City University of Hong Kong, China

Email: [info@imws-amp.org](mailto:info@imws-amp.org)

**IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2025)** is organized by Jiangsu Integrated Circuit Application Technology Innovation Center, and co-organized by City University of Hong Kong Qingdao Innovation Centre, Ceyear Technologies Co. Ltd, Nanjing University of Aeronautics and Astronautics and National University of Singapore (Suzhou) Research Institute, the 55th Research Institute of China Electronics Technology Group Corporation (CETC55) and National Key Laboratory of Solid-State Microwave Devices and Circuits. IMWS-AMP 2025 is a continuation of a series of annual international events held in Suzhou, China (2015), Chengdu, China (2016), Pavia, Italy (2017), Michigan, USA (2018), Bochum, Germany (2019), Suzhou, China (2020), Chongqing, China (2021), Guangzhou, China (2022), Chengdu, China (2023), and Nanjing, China (2024). The purpose of this platform is to boost technical and educational activities as well as exchanges and collaborations within the international microwave community. **IMWS-AMP 2025** will be held in Wuxi, China on **July 23-26, 2025**. IMWS-AMP 2025 will feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches on technology trends and significant advances in relevant topics. Contributed papers are solicited for the same topics as listed below.

#### The topics include, but are not limited to

- Carbon nanotubes and 2D electronic and optoelectronic devices (e.g. graphene and beyond graphene)
- Wide bandgap and other emerging semiconductor materials (e.g. ionic materials) based electronic devices: characterization, modelling and design
- Advanced silicon, integrated passive devices and through substrate via
- Low-temperature co-fired ceramic and liquid crystal polymer based microwave devices
- Large-area printing, inkjet printing and 3D printing materials and processes for RF and THz applications
- Fan-out wafer/panel level packaging for 5G mmWave and IoT, etc.
- Flexible materials for RF electronics and antennas
- Engineered metamaterials and plasmonics for absorption, cloaking, and wave manipulation
- Ferromagnetic materials and superconducting materials
- Spin-wave and magnetic crystal materials
- Passive/active microwave and terahertz devices (material characterization, fabrications, and applications)
- Antennas with advanced/complex/artificial materials and processes
- Advanced applications: wireless communications, radar, imaging, sensing, etc.

#### Electronic Paper Submission:

Prospective authors are invited to submit manuscripts in electronic (PDF) format only. All papers must be written in English and limited to three pages. Papers submitted will be peer-reviewed and all papers presented at the conference will be included in the IEEE Xplore pending quality review. Note that one-page abstracts can also be acceptable, but they will not be included in the IEEE Xplore.

#### Special Issue in IEEE Transactions on Microwave Theory and Techniques (IEEE T-MTT):

Authors of all papers presented at IEEE IMWS-AMP 2025 are invited to submit an expanded version of their papers to a Mini-Special Issue of IEEE T-MTT. A significant extension of the conference paper is required, so that the novelty and quality of the manuscript is the same as that of regular manuscripts of IEEE T-MTT. Every paper will be reviewed in the same manner as all other regular submissions.

#### Best Student Paper Awards:

Awards for Best Student Papers will be presented to the winners at the conference. The Awards Committee will judge the papers primarily on originality, significance, technical soundness, presentation, and reviewers' reports. To qualify for the Best Student Paper, the author must be a full-time student who presents, as the first author, the paper at the conference.

#### PhD Student Travel Grant:

The **PhD Student Travel Grant**, sponsored by IEEE MTT-S, is to invite PhD students from universities and institutes to participate in the conference. Each recipient will receive a grant of **USD \$500** to partially cover their participation expenses. The deadline for the Grant application is **Apr 7, 2025**.

#### Important Dates:

Paper Submission Deadline:	Mar 24, 2025	<b>Apr 7, 2025</b>
Notification of Acceptance:	Apr 28, 2025	
Final paper Submission:	May 19, 2025	

#### Exhibitions:

Exhibition of company products is solicited for the areas related to the topics. Interested parties could contact the Conference Secretariat.

